

# CD74HC259, CD74HCT259

## High Speed CMOS Logic 8-Bit Addressable Latch

### Features

- Buffered Inputs and Outputs
- Four Operating Modes
- Typical Propagation Delay of 15ns at  $V_{CC} = 5V$ ,  $C_L = 15pF$ ,  $T_A = 25^\circ C$
- Fanout (Over Temperature Range)
  - Standard Outputs . . . . . 10 LSTTL Loads
  - Bus Driver Outputs . . . . . 15 LSTTL Loads
- Wide Operating Temperature Range . . .  $-55^\circ C$  to  $125^\circ C$
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HC Types
  - 2V to 6V Operation
  - High Noise Immunity:  $N_{IL} = 30\%$ ,  $N_{IH} = 30\%$  of  $V_{CC}$  at  $V_{CC} = 5V$
- HCT Types
  - 4.5V to 5.5V Operation
  - Direct LSTTL Input Logic Compatibility,  $V_{IL} = 0.8V$  (Max),  $V_{IH} = 2V$  (Min)
  - CMOS Input Compatibility,  $I_I \leq 1\mu A$  at  $V_{OL}$ ,  $V_{OH}$

### Description

The Harris CD74HC259 and CD74HCT259 Addressable Latch features the low-power consumption associated with CMOS circuitry and has speeds comparable to low-power Schottky.

This latches three active modes and one reset mode. When both the Latch Enable ( $\overline{LE}$ ) and Master Reset ( $\overline{MR}$ ) inputs are low (8-line Demultiplexer mode) the output of the addressed latch follows the Data input and all other outputs are forced low. When both  $\overline{MR}$  and  $\overline{LE}$  are high (Memory Mode), all outputs are isolated from the Data input, i.e., all latches hold the last data presented before the  $\overline{LE}$  transition from low to high. A condition of  $\overline{LE}$  low and  $\overline{MR}$  high (Addressable Latch mode) allows the addressed latch's output to follow the data input; all other latches are unaffected. The Reset mode (all outputs low) results when  $\overline{LE}$  is high and  $\overline{MR}$  is low.

### Ordering Information

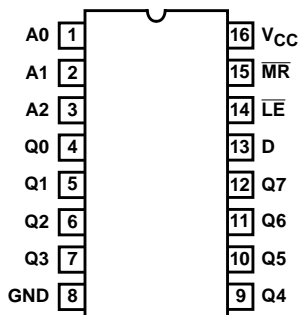
PART NUMBER	TEMP. RANGE ( $^\circ C$ )	PACKAGE	PKG. NO.
CD74HC259E	-55 to 125	16 Ld PDIP	E16.3
CD74HCT259E	-55 to 125	16 Ld PDIP	E16.3
CD74HC259M	-55 to 125	16 Ld SOIC	M16.15
CD74HCT259M	-55 to 125	16 Ld SOIC	M16.15

#### NOTES:

1. When ordering, use the entire part number. Add the suffix 96 to obtain the variant in the tape and reel.
2. Wafer or die for this part number is available which meets all electrical specifications. Please contact your local sales office or Harris customer service for ordering information.

### Pinout

CD74HC259, CD74HCT259  
(PDIP, SOIC)  
TOP VIEW





# CD74HC259, CD74HCT259

## Absolute Maximum Ratings

DC Supply Voltage, $V_{CC}$	-0.5V to 7V
DC Input Diode Current, $I_{IK}$	
For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$	$\pm 20mA$
DC Output Diode Current, $I_{OK}$	
For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$	$\pm 20mA$
DC Drain Current, per Output, $I_O$	
For $-0.5V < V_O < V_{CC} + 0.5V$	$\pm 25mA$
DC Output Source or Sink Current per Output Pin, $I_O$	
For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$	$\pm 25mA$
DC $V_{CC}$ or Ground Current, $I_{CC}$ or $I_{GND}$	$\pm 50mA$

## Thermal Information

Thermal Resistance (Typical, Note 3)	$\theta_{JA}$ ( $^{\circ}C/W$ )
PDIP Package	90
SOIC Package	115
Maximum Junction Temperature	150 $^{\circ}C$
Maximum Storage Temperature Range	-65 $^{\circ}C$ to 150 $^{\circ}C$
Maximum Lead Temperature (Soldering 10s)	300 $^{\circ}C$ (SOIC - Lead Tips Only)

## Operating Conditions

Temperature Range, $T_A$	-55 $^{\circ}C$ to 125 $^{\circ}C$
Supply Voltage Range, $V_{CC}$	
HC Types	.2V to 6V
HCT Types	.4.5V to 5.5V
DC Input or Output Voltage, $V_I$ , $V_O$	0V to $V_{CC}$
Input Rise and Fall Time	
2V	1000ns (Max)
4.5V	500ns (Max)
6V	400ns (Max)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

- $\theta_{JA}$  is measured with the component mounted on an evaluation PC board in free air.

## DC Electrical Specifications

PARAMETER	SYMBOL	TEST CONDITIONS		V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		V <sub>I</sub> (V)	I <sub>O</sub> (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HC TYPES												
High Level Input Voltage	V <sub>IH</sub>	-	-	2	1.5	-	-	1.5	-	1.5	-	V
				4.5	3.15	-	-	3.15	-	3.15	-	V
				6	4.2	-	-	4.2	-	4.2	-	V
Low Level Input Voltage	V <sub>IL</sub>	-	-	2	-	-	0.5	-	0.5	-	0.5	V
				4.5	-	-	1.35	-	1.35	-	1.35	V
				6	-	-	1.8	-	1.8	-	1.8	V
High Level Output Voltage CMOS Loads	V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub>	-0.02	2	1.9	-	-	1.9	-	1.9	-	V
			-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
			-0.02	6	5.9	-	-	5.9	-	5.9	-	V
-			-	-	-	-	-	-	-	-	V	
-4			4.5	3.98	-	-	3.84	-	3.7	-	V	
-5.2			6	5.48	-	-	5.34	-	5.2	-	V	
High Level Output Voltage TTL Loads	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.02	2	-	-	0.1	-	0.1	-	0.1	V
			0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
			0.02	6	-	-	0.1	-	0.1	-	0.1	V
-			-	-	-	-	-	-	-	-	V	
4			4.5	-	-	0.26	-	0.33	-	0.4	V	
5.2			6	-	-	0.26	-	0.33	-	0.4	V	
Low Level Output Voltage CMOS Loads	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.02	2	-	-	0.1	-	0.1	-	0.1	V
			0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
			0.02	6	-	-	0.1	-	0.1	-	0.1	V
-			-	-	-	-	-	-	-	-	V	
4			4.5	-	-	0.26	-	0.33	-	0.4	V	
5.2			6	-	-	0.26	-	0.33	-	0.4	V	
Low Level Output Voltage TTL Loads	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.02	2	-	-	0.1	-	0.1	-	0.1	V
			0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
			0.02	6	-	-	0.1	-	0.1	-	0.1	V
-			-	-	-	-	-	-	-	-	V	
4			4.5	-	-	0.26	-	0.33	-	0.4	V	
5.2			6	-	-	0.26	-	0.33	-	0.4	V	
Input Leakage Current	I <sub>I</sub>	V <sub>CC</sub> or GND	-	6	-	-	±0.1	-	±1	-	±1	μA

# CD74HC259, CD74HCT259

## DC Electrical Specifications (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS		V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		V <sub>I</sub> (V)	I <sub>O</sub> (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
Quiescent Device Current	I <sub>CC</sub>	V <sub>CC</sub> or GND	0	6	-	-	8	-	80	-	160	μA
<b>HCT TYPES</b>												
High Level Input Voltage	V <sub>IH</sub>	-	-	4.5 to 5.5	2	-	-	2	-	2	-	V
Low Level Input Voltage	V <sub>IL</sub>	-	-	4.5 to 5.5	-	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage CMOS Loads	V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub>	-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
High Level Output Voltage TTL Loads			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
Low Level Output Voltage CMOS Loads	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			4	4.5	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I <sub>I</sub>	V <sub>CC</sub> and GND	0	5.5	-		±0.1	-	±1	-	±1	μA
Quiescent Device Current	I <sub>CC</sub>	V <sub>CC</sub> or GND	0	5.5	-	-	8	-	80	-	160	μA
Additional Quiescent Device Current Per Input Pin: 1 Unit Load	ΔI <sub>CC</sub>	V <sub>CC</sub> -2.1	-	4.5 to 5.5	-	100	360	-	450	-	490	μA

NOTE: For dual-supply systems theoretical worst case (V<sub>I</sub> = 2.4V, V<sub>CC</sub> = 5.5V) specification is 1.8mA.

## HCT Input Loading Table

INPUT	UNIT LOADS
A0 - A2, $\overline{LE}$	1.5
D	1.2
$\overline{MR}$	0.75

NOTE: Unit Load is ΔI<sub>CC</sub> limit specified in DC Electrical Table, e.g., 360μA max at 25°C.

## Prerequisite for Switching Specifications

PARAMETER	SYMBOL	V <sub>CC</sub> (V)	25°C			-40°C TO 85°C			-55°C TO 125°C			UNITS
			MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
HC TYPES												
Pulse Width LE	t <sub>WL</sub>	2	70	-	-	90	-	-	105	-	-	ns
		4.5	14	-	-	18	-	-	21	-	-	ns
		6	12	-	-	15	-	-	18	-	-	ns

# CD74HC259, CD74HCT259

## Prerequisite for Switching Specifications (Continued)

PARAMETER	SYMBOL	V <sub>CC</sub> (V)	25°C			-40°C TO 85°C			-55°C TO 125°C			UNITS
			MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
MR	t <sub>WL</sub>	2	70	-	-	90	-	-	105	-	-	ns
		4.5	14	-	-	18	-	-	21	-	-	ns
		6	12	-	-	15	-	-	18	-	-	ns
Setup Time D to $\overline{LE}$ A to $\overline{LE}$	t <sub>SU</sub>	2	80	-	-	100	-	-	120	-	-	ns
		4.5	16	-	-	20	-	-	24	-	-	ns
		6	14	-	-	17	-	-	20	-	-	ns
Hold Time D to $\overline{LE}$ A to $\overline{LE}$	t <sub>H</sub>	2	0	-	-	0	-	-	0	-	-	ns
		4.5	0	-	-	0	-	-	0	-	-	ns
		6	0	-	-	0	-	-	0	-	-	ns
HCT TYPES												
Pulse Width $\overline{LE}$ MR	t <sub>WL</sub>	4.5	18	-	-	23	-	-	27	-	-	ns
Setup Time D to $\overline{LE}$ A to $\overline{LE}$	t <sub>SU</sub>	4.5	17	-	-	21	-	-	26	-	-	ns
Hold Time D to $\overline{LE}$ A to $\overline{LE}$	t <sub>H</sub>	4.5	0	-	-	0	-	-	0	-	-	ns

## Switching Specifications C<sub>L</sub> = 50pF, Input t<sub>r</sub>, t<sub>f</sub> = 6ns

PARAMETER	SYMBOL	TEST CONDITIONS	V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HC TYPES											
Propagation Delay D to Q	t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	-	-	185	-	230	-	280	ns
			4.5	-	-	37	-	46	-	56	ns
		C <sub>L</sub> = 15pF	5	-	15	-	-	-	-	-	ns
		C <sub>L</sub> = 50pF	6	-	-	31	-	39	-	48	ns
$\overline{LE}$ to Q	t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	-	-	170	-	215	-	255	ns
			4.5	-	-	34	-	43	-	51	ns
		C <sub>L</sub> = 15pF	5	-	14	-	-	-	-	-	ns
		C <sub>L</sub> = 50pF	6	-	-	29	-	37	-	43	ns

# CD74HC259, CD74HCT259

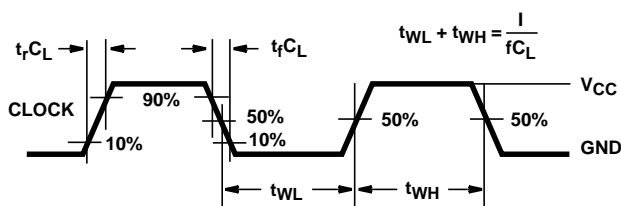
## Switching Specifications $C_L = 50\text{pF}$ , Input $t_r$ , $t_f = 6\text{ns}$ (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS	V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS	
				MIN	TYP	MAX	MIN	MAX	MIN	MAX		
A to Q	t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	-	-	185	-	230	-	280	ns	
			4.5	-	-	37	-	46	-	56	ns	
		C <sub>L</sub> = 15pF	5	-	15	-	-	-	-	-	ns	
		C <sub>L</sub> = 50pF	6	-	-	31	-	39	-	48	ns	
MR to Q	t <sub>PHL</sub> , t <sub>PLH</sub>	C <sub>L</sub> = 50pF	2	-	-	155	-	195	-	235	ns	
			4.5	-	-	31	-	39	-	47	ns	
		C <sub>L</sub> = 15pF	5	-	13	-	-	-	-	-	ns	
		C <sub>L</sub> = 50pF	6	-	-	26	-	33	-	40	ns	
Output Transition Time	t <sub>THL</sub> , t <sub>TLH</sub>	C <sub>L</sub> = 50pF	2	-	-	75	-	95	-	110	ns	
			4.5	-	-	15	-	19	-	22	ns	
			6	-	-	13	-	16	-	19	ns	
Power Dissipation Capacitance (Notes 4, 5)	C <sub>PD</sub>	C <sub>L</sub> = 15pF	5	-	21	-	-	-	-	-	pF	
Input Capacitance	C <sub>I</sub>	C <sub>L</sub> = 50pF	-	10	-	10	-	10	-	10	pF	
HCT TYPES												
Propagation Delay D to Q	t <sub>PHL</sub> , t <sub>PLH</sub>	C <sub>L</sub> = 50pF	4.5	-	-	39	-	49	-	59	ns	
		C <sub>L</sub> = 15pF	5	-	16	-	-	-	-	-	ns	
		LE to Q	C <sub>L</sub> = 50pF	4.5	-	-	38	-	48	-	57	ns
			C <sub>L</sub> = 15pF	5	-	16	-	-	-	-	-	ns
		A to Q	C <sub>L</sub> = 50pF	4.5	-	-	41	-	51	-	61	ns
			C <sub>L</sub> = 15pF	5	-	17	-	-	-	-	-	ns
		MR to Q	C <sub>L</sub> = 50pF	4.5	-	-	39	-	49	-	59	ns
			C <sub>L</sub> = 15pF	5	-	16	-	-	-	-	-	ns
Power Dissipation Capacitance (Notes 4, 5)	C <sub>PD</sub>	C <sub>L</sub> = 15pF	5	-	22	-	-	-	-	-	pF	
Input Capacitance	C <sub>I</sub>	C <sub>L</sub> = 50pF	-	10	-	10	-	10	-	10	pF	
Output Transition Time	t <sub>THL</sub> , t <sub>TLH</sub>	C <sub>L</sub> = 50pF	4.5	-	-	15	-	19	-	22	ns	

### NOTES:

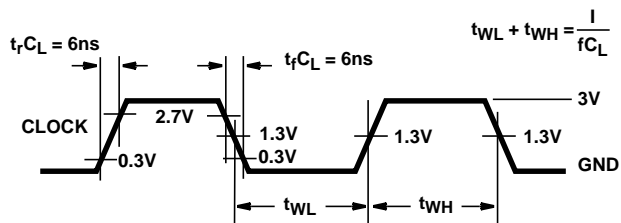
- $C_{PD}$  is used to determine the dynamic power consumption, per package.
- $P_D = C_{PD} V_{CC}^2 f_i + \sum C_L V_{CC}^2 f_O$  where  $f_i$  = Input Frequency,  $f_O$  = Output Frequency,  $C_L$  = Output Load Capacitance,  $V_{CC}$  = Supply Voltage.

# Test Circuits and Waveforms



NOTE: Outputs should be switching from 10%  $V_{CC}$  to 90%  $V_{CC}$  in accordance with device truth table. For  $f_{MAX}$ , input duty cycle = 50%.

FIGURE 1. HC CLOCK PULSE RISE AND FALL TIMES AND PULSE WIDTH



NOTE: Outputs should be switching from 10%  $V_{CC}$  to 90%  $V_{CC}$  in accordance with device truth table. For  $f_{MAX}$ , input duty cycle = 50%.

FIGURE 2. HCT CLOCK PULSE RISE AND FALL TIMES AND PULSE WIDTH

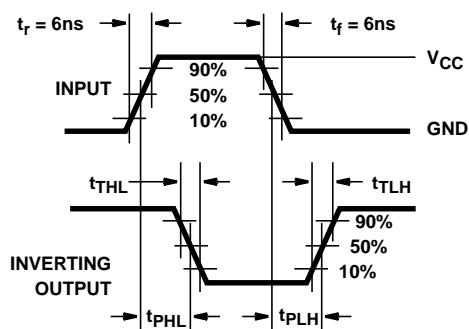


FIGURE 3. HC TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

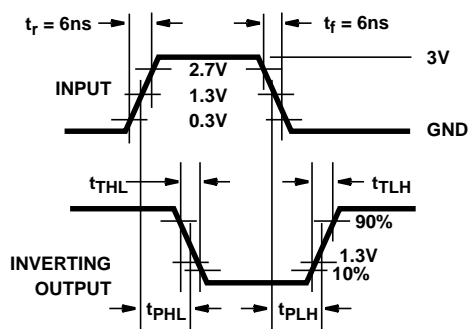


FIGURE 4. HCT TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

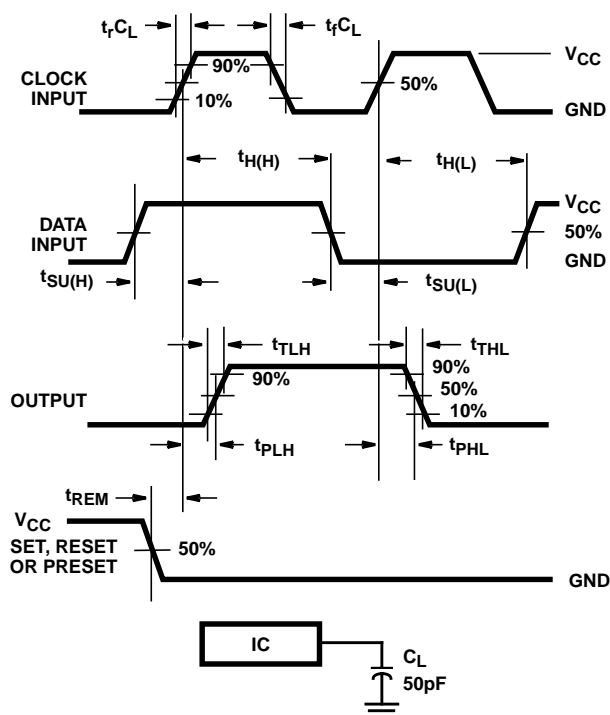


FIGURE 5. HC SETUP TIMES, HOLD TIMES, REMOVAL TIME, AND PROPAGATION DELAY TIMES FOR EDGE TRIGGERED SEQUENTIAL LOGIC CIRCUITS

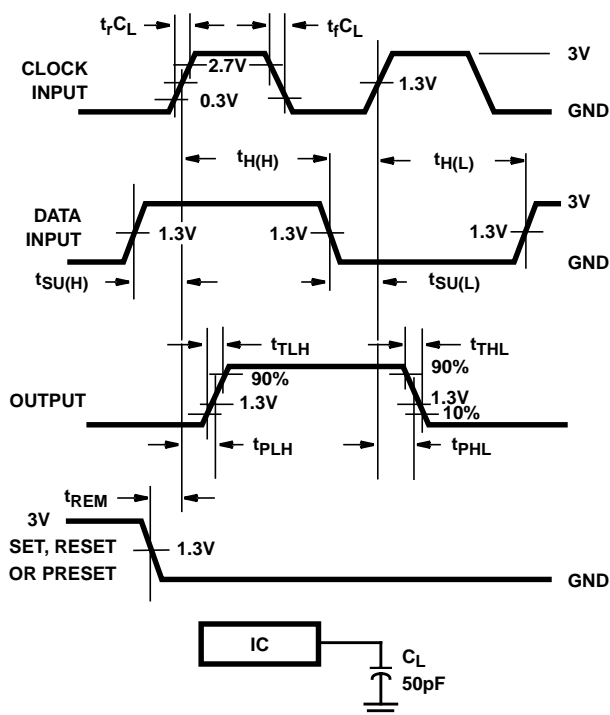
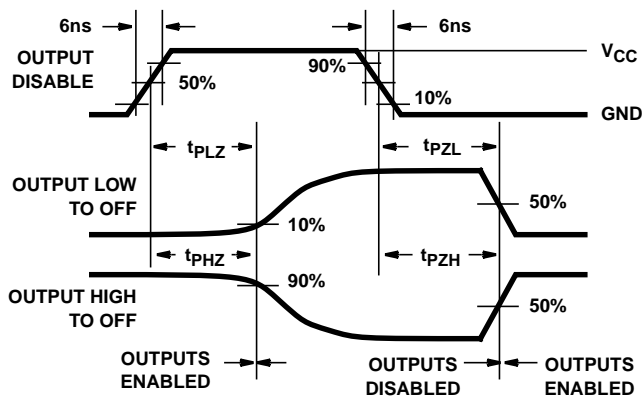
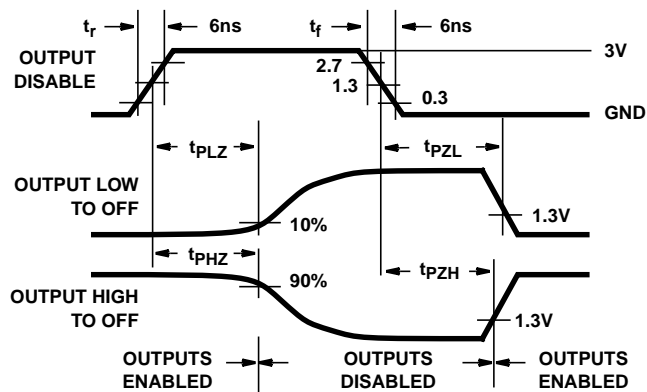


FIGURE 6. HCT SETUP TIMES, HOLD TIMES, REMOVAL TIME, AND PROPAGATION DELAY TIMES FOR EDGE TRIGGERED SEQUENTIAL LOGIC CIRCUITS

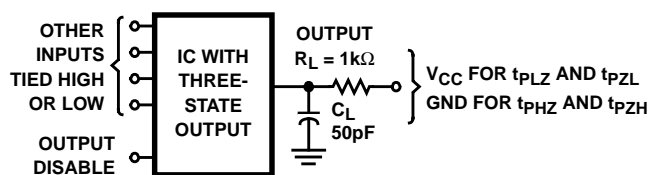
**Test Circuits and Waveforms** (Continued)



**FIGURE 7. HC THREE-STATE PROPAGATION DELAY WAVEFORM**



**FIGURE 8. HCT THREE-STATE PROPAGATION DELAY WAVEFORM**



NOTE: Open drain waveforms  $t_{PLZ}$  and  $t_{PZL}$  are the same as those for three-state shown on the left. The test circuit is Output  $R_L = 1k\Omega$  to  $V_{CC}$ ,  $C_L = 50pF$ .

**FIGURE 9. HC AND HCT THREE-STATE PROPAGATION DELAY TEST CIRCUIT**



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